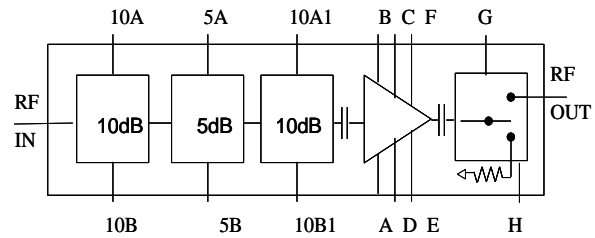


## 6-18GHz 3 bit Digital Variable Amplifier

### GaAs Monolithic Microwave IC

#### Description

The CHA3513-99F is composed by a three steps digital attenuator followed by a three stage travelling amplifier and a Single Pole Single Through (SPST) switch. It is designed for defense applications. The backside of the chip is both RF and DC grounded. This helps to simplify the assembly process.



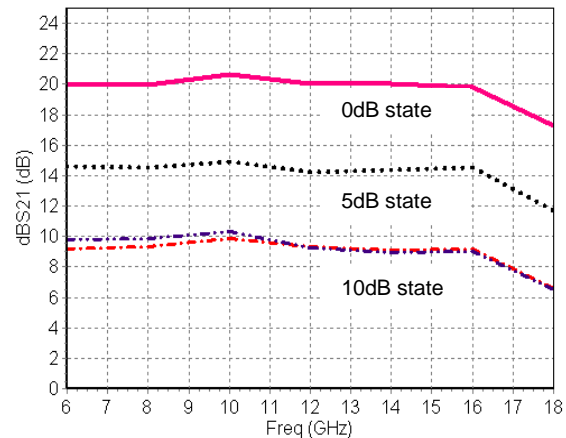
The circuit is manufactured with a pHEMT process, 0.25µm gate length, via holes through the substrate, air bridges and electron beam gate lithography.

It is available in chip form.

#### Main Features

- Performances: 6-18GHz
- 20dBm saturated output power
- 19 dB gain
- 3 bit attenuator for 26dB range
- DC power consumption, 300mA @ 4.5V
- Chip size: 6.68 x 2.46 x 0.1mm

Typical on wafer Measurements  
Gain versus attenuation states



#### Main Characteristics

Tamb. = 25°C

| Symbol  | Parameter                                     | Min | Typ | Max | Unit |
|---------|---|-----|-----|-----|------|
| Fop     | Operating frequency range                     | 6   |     | 18  | GHz  |
| G       | Small signal gain @ Attenuator state 0dB      |     | 19  |     | dB   |
| Psat    | Saturated Output power @ Attenuator state 0dB |     | 20  |     | dBm  |
| ATT dyn | Attenuator range with 3bit                    |     | 25  |     | dB   |

ESD Protection : Electrostatic discharge sensitive device. Observe handling precautions !

## Electrical Characteristics on wafer

Tamb = +25°C

Vd = Pads B, D, F = 4.5V, Vg = Pads A, C, E tuned for Id = 300mA

| Symbol  | Parameter  | Min | Typ | Max | Unit |
|---------|--|-----|-----|-----|------|
| Fop     | Operating frequency range (1)                              | 6   |     | 18  | GHz  |
| G       | Small signal gain @ Attenuator state 0dB (1)<br>6-17GHz    | 17  | 19  |     | dB   |
|         | 17-18GHz   | 15  | 16  |     | dB   |
| ATT bit | Attenuator bit: State 5dB                                  | 4.5 | 5   | 6.5 | dB   |
|         | State 10 dB 1  | 9.5 | 10  | 12  | dB   |
|         | State 10dB 2   | 9.5 | 10  | 12  | dB   |
| ATT dyn | Attenuator range with 3bit                                 |     | 25  |     | dB   |
| Is      | Small signal gain @ Attenuator state 0dB & switch OFF (1)  |     | -35 |     | dB   |
| P1dB    | Output power at 1dB compression @ Attenuator state 0dB (1) |     | 18  |     | dBm  |
| Psat    | Saturated Output power @ Attenuator state 0dB (1)          |     | 20  |     | dBm  |
| NF      | Noise figure @ Attenuator state 0dB                        |     | 12  |     | dB   |
| RL_IN   | Input Return Loss all attenuator states                    |     | -15 | -9  | dB   |
| RL_OUT  | Output Return Loss all attenuator states & switch ON       |     | -15 | -9  | dB   |
| Vd      | Drain bias DC voltage (Pads B, D, F)                       |     | 4.5 |     | V    |
| Id      | Bias current @ small signal                                |     | 300 | 350 | mA   |
| Vc      | Control voltage for Attenuator bits & SPST switch          | -5  |     | 0   | V    |

(1) These values are representative of on-wafer measurements that are made without bonding wires at the RF ports.

**Absolute Maximum Ratings**

Tamb. = 25°C (1)

| Symbol | Parameter                                | Values      | Unit |
|--------|--|-------------|------|
| Vd     | Maximum Drain bias voltage ( Pads B,D,F) | +5          | V    |
| Id     | Drain bias current with Vd=4.5V          | 450         | mA   |
| Vg     | Gate bias voltage (Pads A,C,E)           | -2 to +0.4  | V    |
| Vc     | Attenuator bits & SPST control voltage   | -7 to +0.6  | V    |
| Pin    | Maximum input power overdrive (2)        | +20.0       | dBm  |
| Tch    | Maximum channel temperature              | +175        | °C   |
| Ta     | Operating temperature range              | -40 to +70  | °C   |
| Tstg   | Storage temperature range                | -55 to +150 | °C   |

(1) Operation of this device above anyone of these parameters may cause permanent damage.

(2) Duration &lt; 1s.

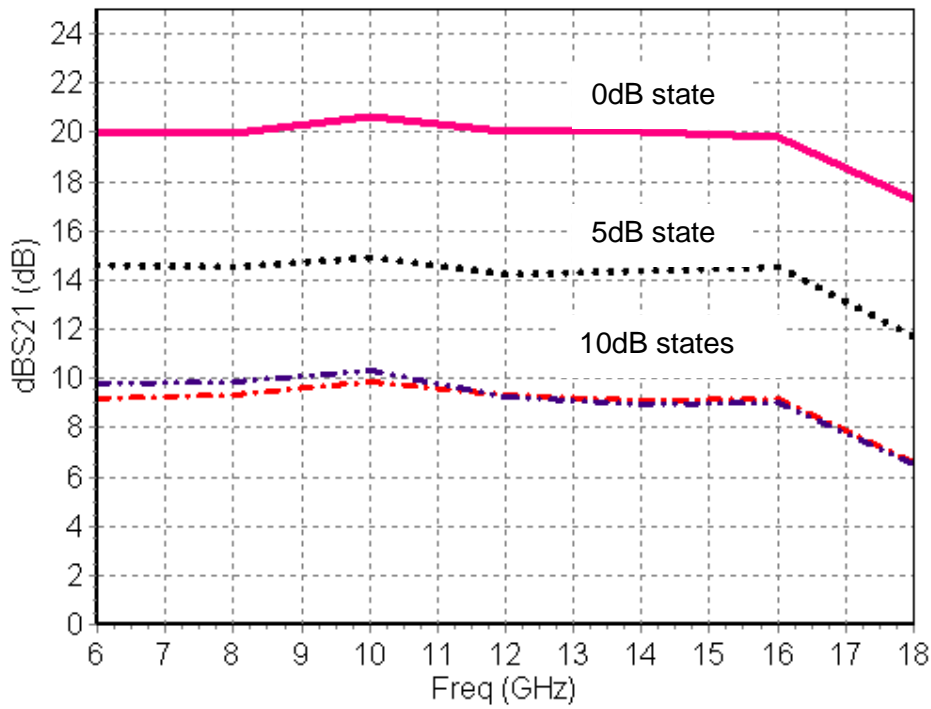
**3bit VGA Control interface**

The attenuator states are controlled by 6 voltages. The SPST switch is controlled by 2 voltages.

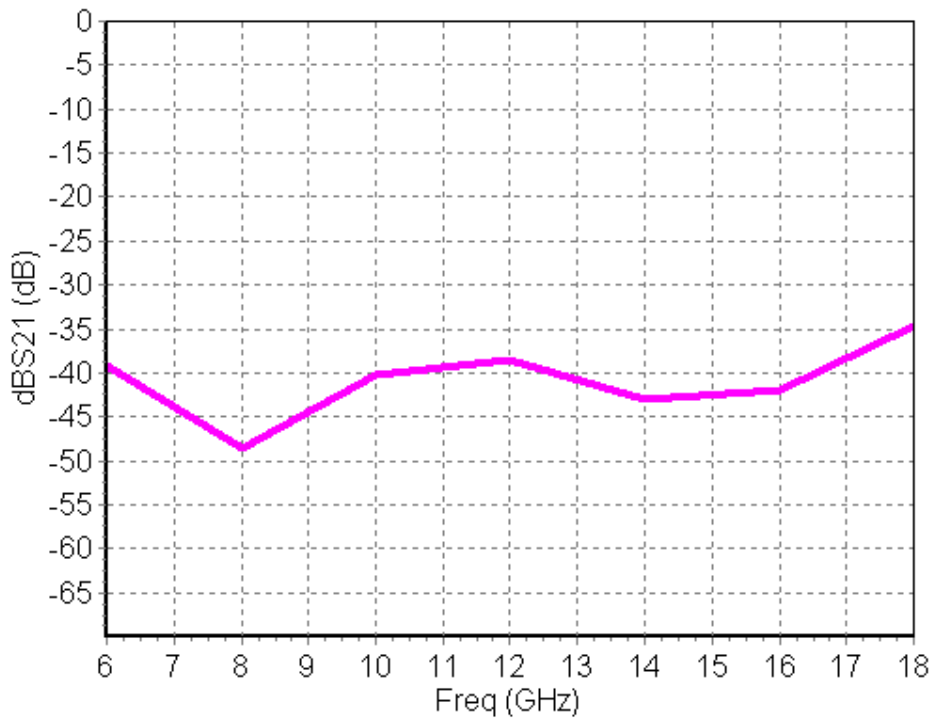
| state | Theoretical attenuation dB | Voltage CONTROL PAD |         |        |        |          |          | Switch control |    |
|-------|----------------------------|---------------------|---------|--------|--------|----------|----------|----------------|----|
|       |                            | 10A (V)             | 10B (V) | 5A (V) | 5B (V) | 10A1 (V) | 10B1 (V) | G              | H  |
| 0     | 0 référence                | -5                  | 0       | -5     | 0      | -5       | 0        | -5             | 0  |
| 1     | 5                          | -5                  | 0       | 0      | -5     | -5       | 0        | -5             | 0  |
| 2     | 10 config.1                | 0                   | -5      | -5     | 0      | -5       | 0        | -5             | 0  |
| 3     | 15 config.1                | 0                   | -5      | 0      | -5     | -5       | 0        | -5             | 0  |
| 4     | 15 config.2                | -5                  | 0       | 0      | -5     | 0        | -5       | -5             | 0  |
| 6     | 10 config.2                | -5                  | 0       | -5     | 0      | 0        | -5       | -5             | 0  |
| 7     | 25                         | 0                   | -5      | 0      | -5     | 0        | -5       | -5             | 0  |
| 8     | Isolation                  | -5                  | 0       | -5     | 0      | -5       | 0        | 0              | -5 |

## Typical on wafer Measurements @ 25°C

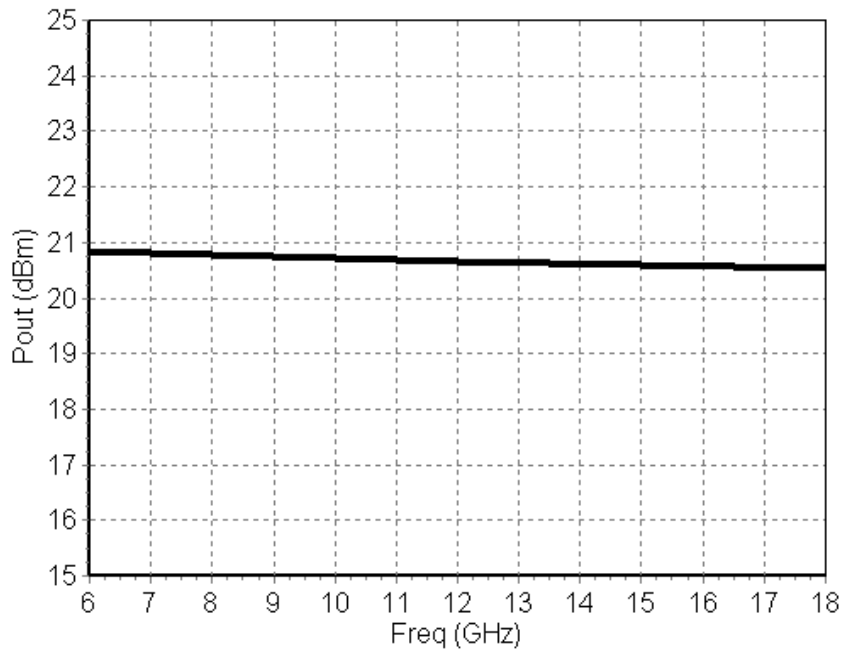
Bias conditions:  $V_d = 4.5V$ ,  $V_g$  tuned for  $I_d = 300mA$



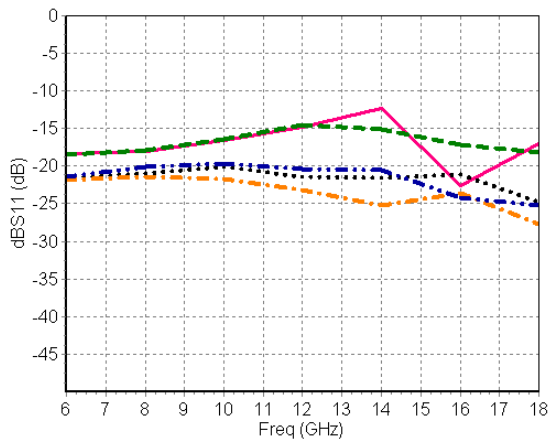
**Linear Gain versus attenuator states**



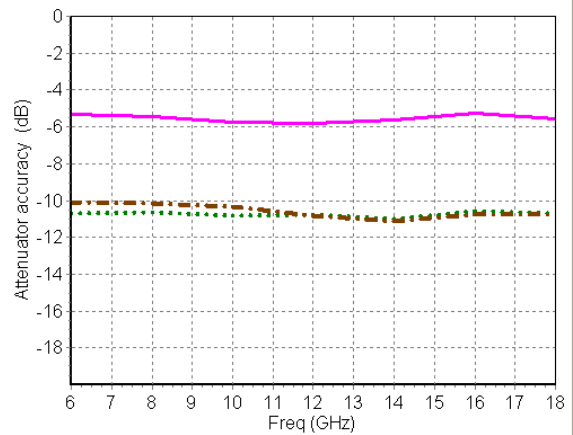
**Linear Gain with SPST switch OFF**



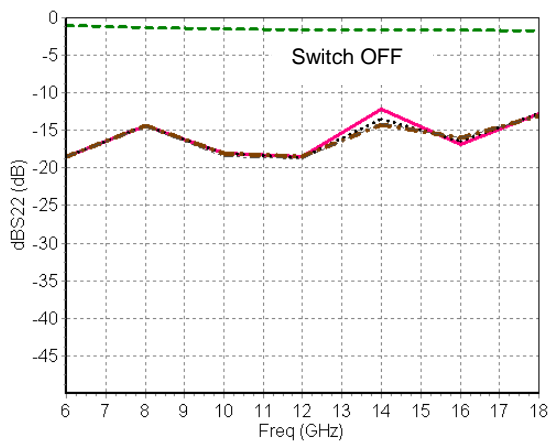
Saturated output power @ nominal state



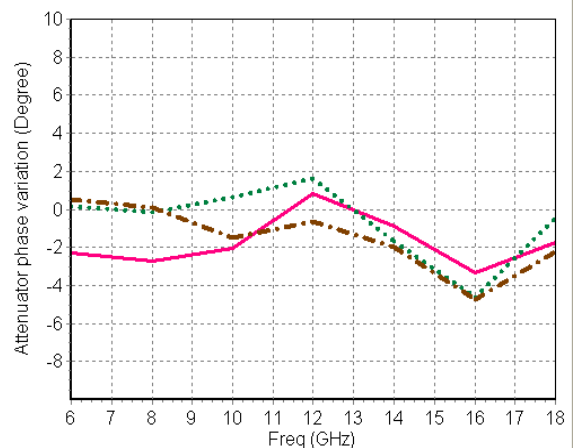
dB(S11) versus frequency for all state



Attenuator value versus frequency for all states



dB(S22) versus frequency for all states

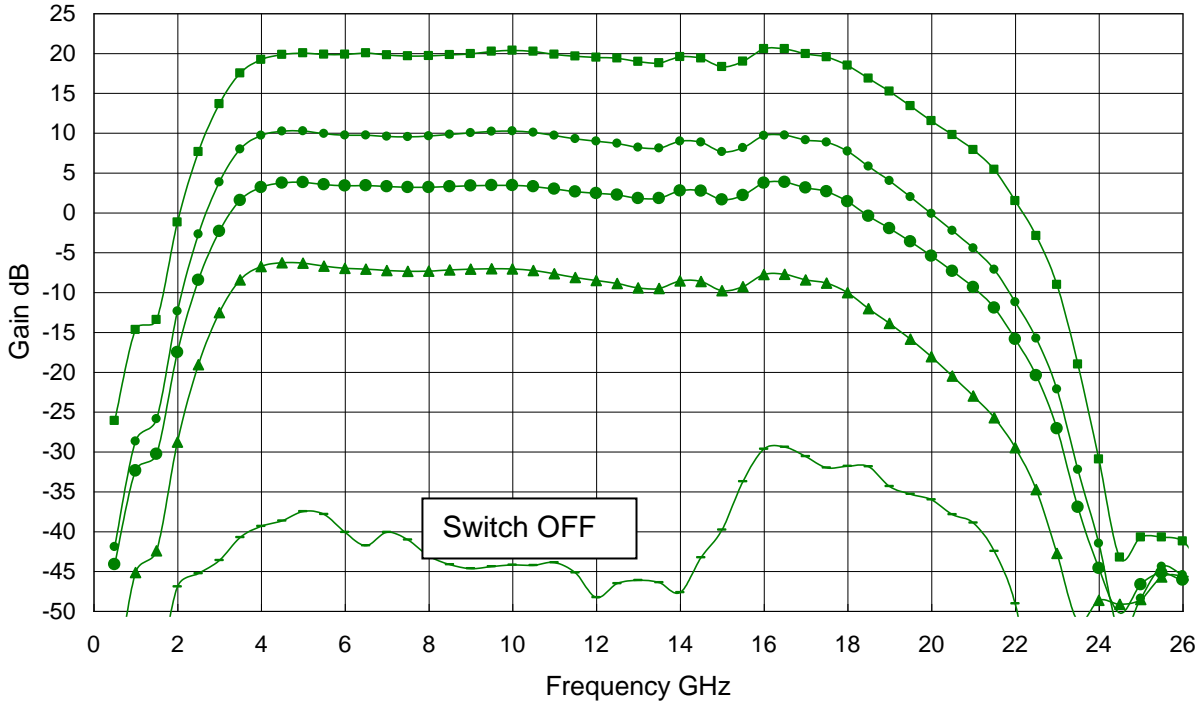


Attenuator phase variation versus frequency for all

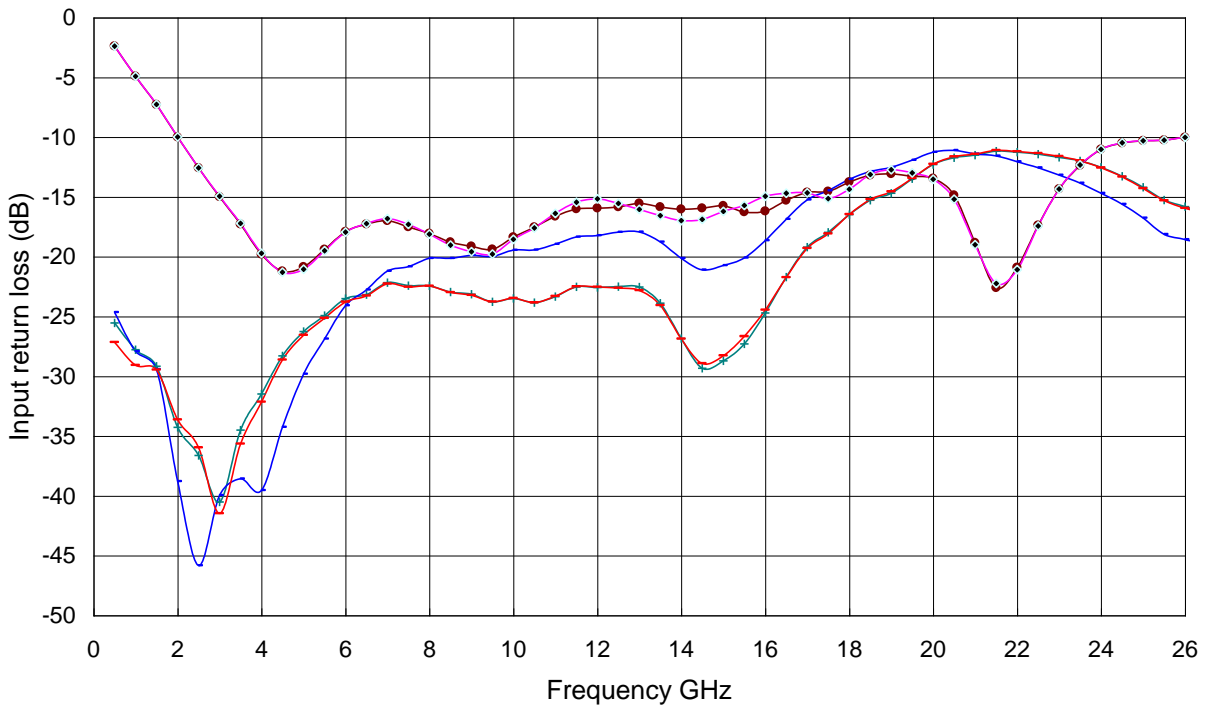
## Typical test fixture Measurements @ 25°C

Bias conditions:  $V_d = 4.5V$ ,  $V_g$  tuned for  $I_d = 300mA$

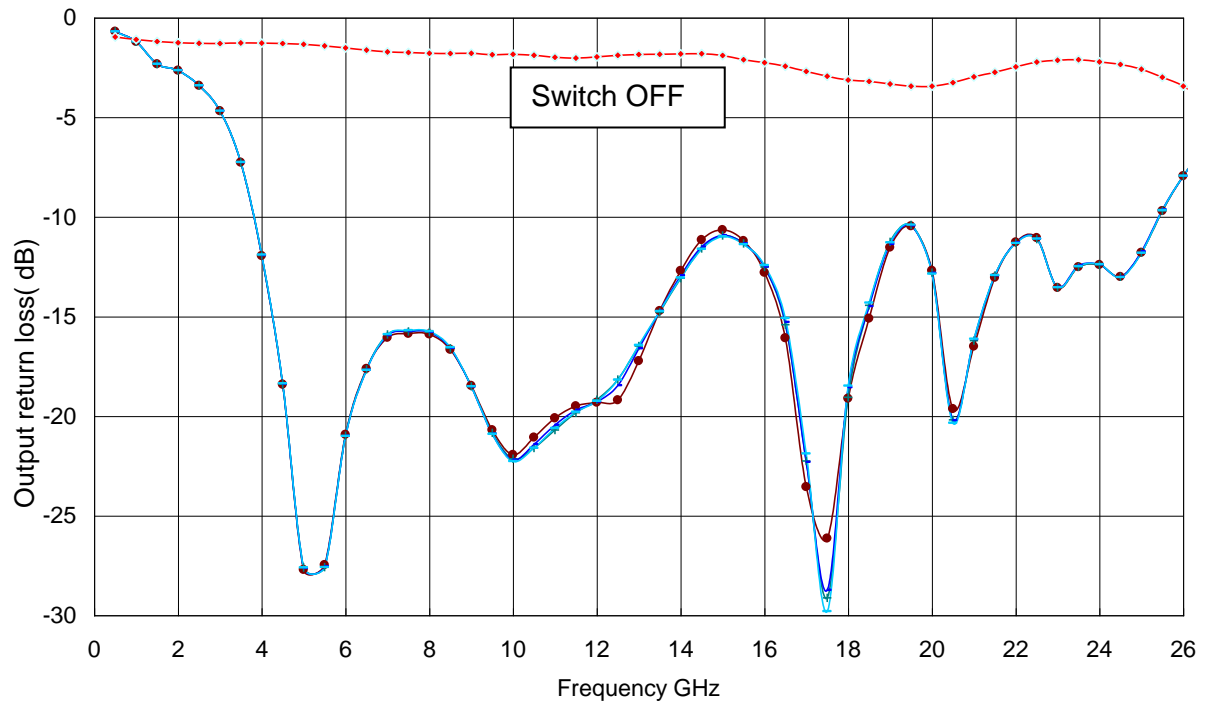
### Linear Gain versus attenuation states



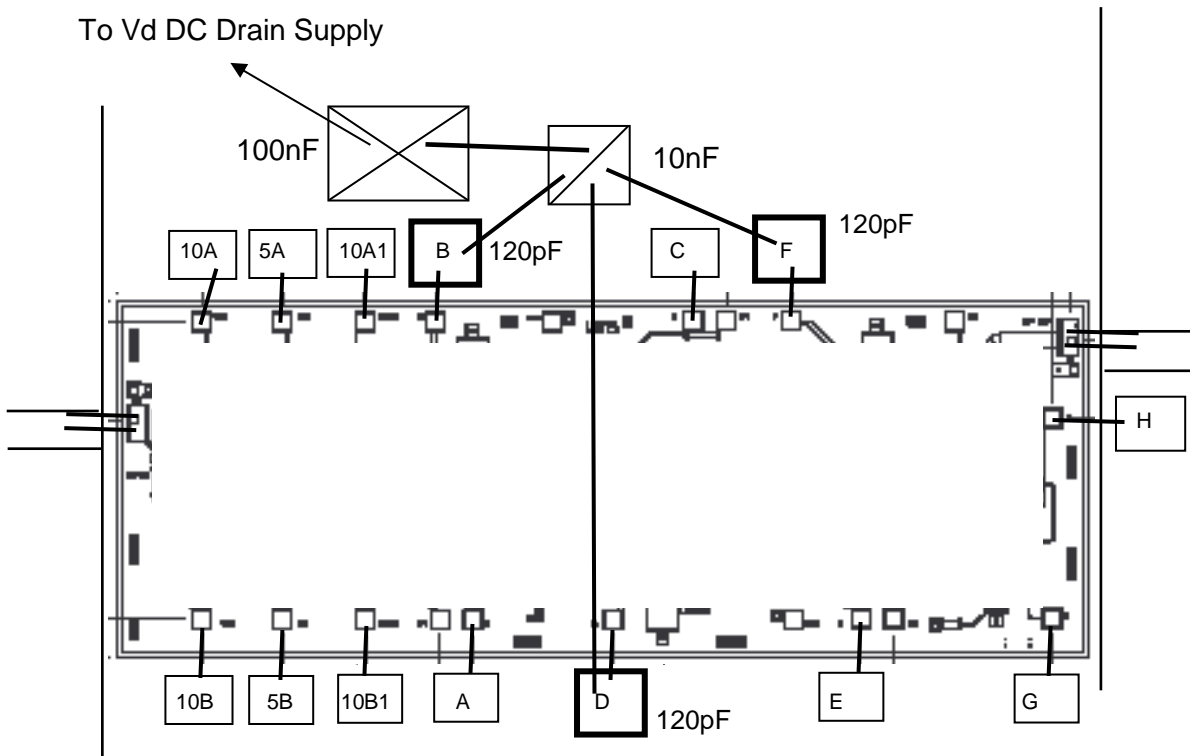
### Input Return Loss versus attenuation states



Output Return Loss versus attenuation states



**Chip Assembly and Mechanical Data**



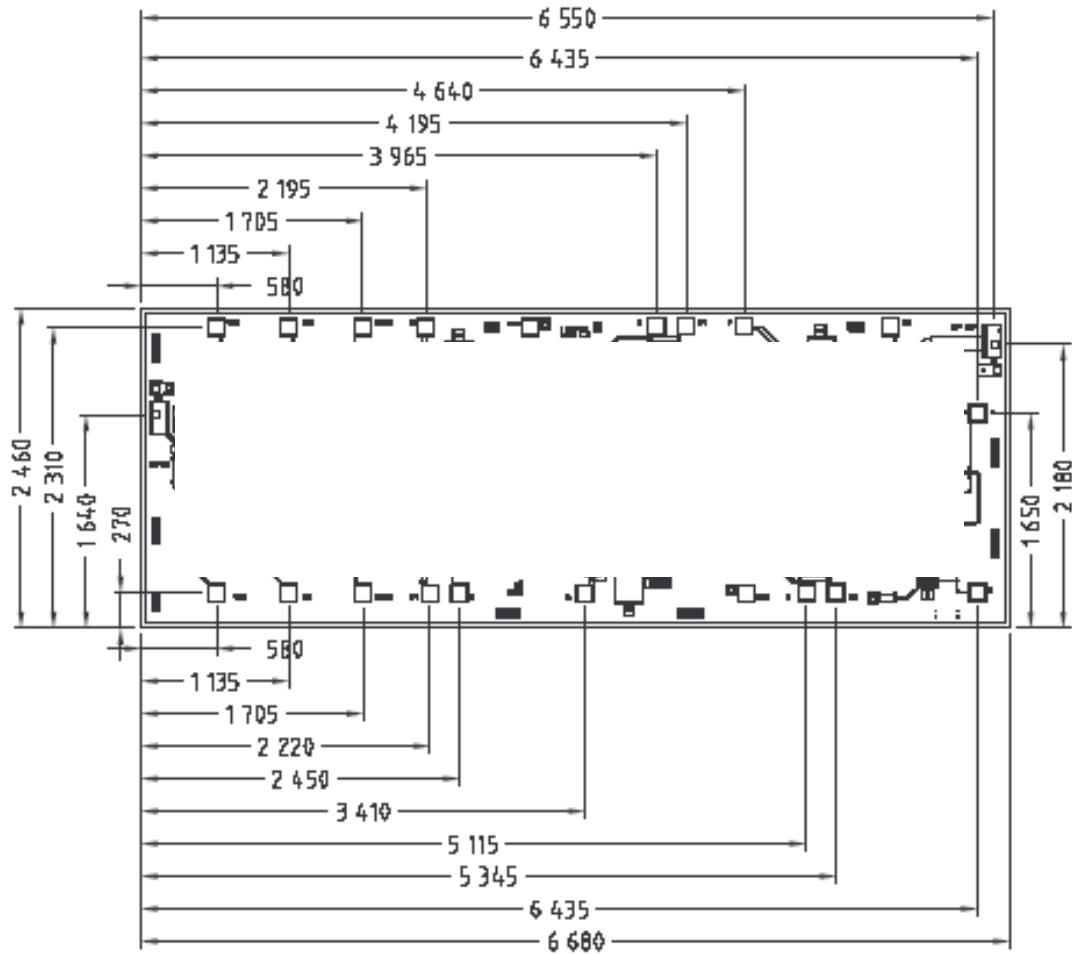
Note: Supply feed should be capacitively bypassed. 25µm diameter gold wire is to be preferred.

**Recommended circuit bonding table**

| Label      | Type | Decoupling          | Comment                 |
|------------|------|---------------------|-------------------------|
| 10A, 10B   | Vc   | <i>Not required</i> | First 10dB pad control  |
| 5A, 5B     | Vc   | <i>Not required</i> | 5dB pad control         |
| 10A1, 10B1 | Vc   | <i>Not required</i> | Second 10dB pad control |
| B          | Vd   | 120pF / 10nF        | Drain Supply            |
| D          | Vd   | 120pF / 10nF        | Drain Supply            |
| F          | Vd   | 120pF / 10nF        | Drain Supply            |
| A          | Vg   | <i>Not required</i> | Gate Supply             |
| C          | Vg   | <i>Not required</i> | Gate Supply             |
| E          | Vg   | <i>Not required</i> | Gate Supply             |
| H          | Vc   | <i>Not required</i> | Switch control          |
| G          | Vc   | <i>Not required</i> | Switch control          |



**Bonding pad positions**



UNITS :  $\mu\text{m}$   
 Tol :  $\pm 35\mu\text{m}$

(Chip thickness:  $100\mu\text{m}$ )

## Ordering Information

Chip form : CHA3513-99F/00

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